



motivair

DIRECT-TO-CHIP COOLING

Dynamic Cold Plate

Choose Your Own Path with Dynamic Liquid Cooling

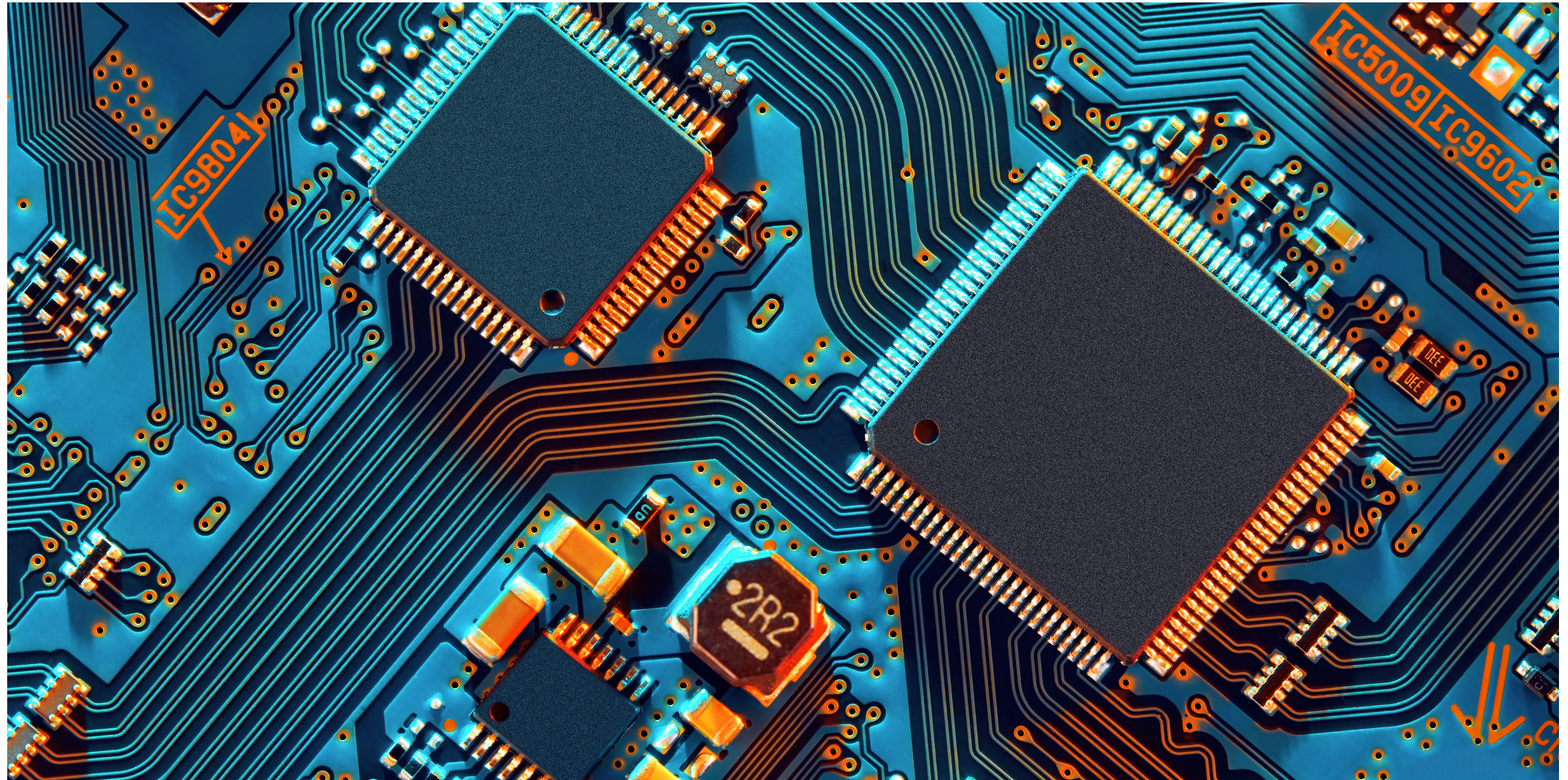
Our patented technology focuses flow to chip hotspots where it's needed most

Motivair's Dynamic® Cold Plates harnesses innovative fluid dynamics to redefine direct liquid cooling.

The free-flowing nature of the Dynamic® Cold Plate accelerates particles and other contaminants moving through and minimizes risks of poor water quality. Our patented technology enables robust performance and allows CPUs, GPUs, APUs, and FPGAs to operate at peak performance while reducing the the possibility of cooling degradation and costly system failures.

This simple yet effective technology is optimized for cost efficient and scalable production, targeted specifically for high-performance computing, small-to-large clusters and Exascale class systems.

All products are engineered and manufactured in the USA, ensuring a predictable, end-to-end experience while eliminating the risks of foreign supply chain disruptions.



DYNAMIC® COLD PLATE MODELS

<p>AMD SP5 GENOA PROCESSOR FAMILY</p>	<p>AMD SP3 MILAN PROCESSOR FAMILY</p>	<p>AMD INSTINCT MI300</p>	<p>INTEL® XEON® SCALABLE PROCESSOR FAMILY (SAPPHIRE RAPIDS)</p>	<p>NVIDIA SXM5 PROCESSOR FAMILY (H100 GPU)</p>	<p>INTEL® XEON® SCALABLE PROCESSOR FAMILY (ICE LAKE)</p>
					

FEATURES

- 1 PATENTED THERMAL TECHNOLOGY**

Our technology harnesses innovative fluid dynamics to redefine direct liquid cooling.
- 2 SCALABLE TO +1000 WATTS**

Single-phase DLC offers accelerated performance, scalability out to at least 1,500 watts per processor, a key performance point enabling AI and a broader adoption of HPC in enterprise data centers.
- 3 NON-FOULING DESIGN**

Operate at peak performance while reducing the possibility of cooling degradation and costly system failures.
- 4 PUSHLOK CONNECTIONS**

Seamless, make-or-break connection of water transfer lines
- 5 MADE IN THE USA**

Ensure a predictable, end to end experience while eliminating the risks of foreign supply chain disruptions.

Solve Today's and Tomorrow's Thermal Challenges

When it comes to addressing thermal challenges, you need to consider the end-to-end solution as a whole – from the silicon out. Our team of engineers will work with you, leveraging our flexible and broad product offerings to design optimized solutions for you based on your unique chip designs.



IN-RACK MANIFOLD

Motivair's stainless steel manifolds provide a common connection point between Motivair's Dynamic™ Cold Plates and the supply and return cooling infrastructure system or Coolant Distribution Unit.

Features

- 304 Stainless Steel
- Variable Size Options 42U/48U/50U/Custom
- Universal Top/Bottom Design
- Made in USA

QUICK CONNECTS

Quick Connects provide a seamless, make-or-break connection of water transfer lines for Motivair's Dynamic™ Cold Plates

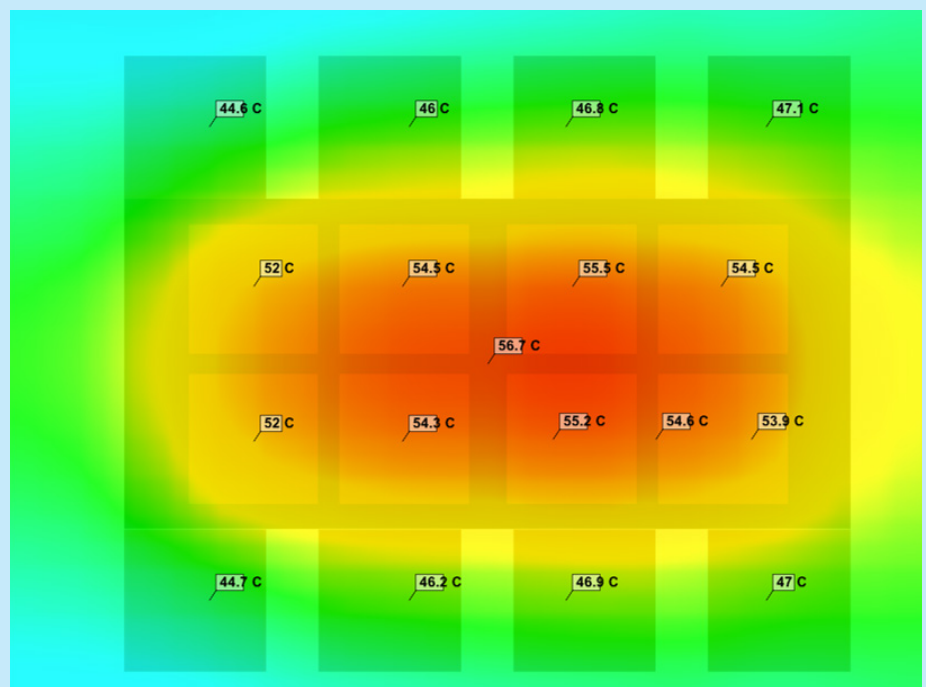
Features

- Designed from the ground up for data center liquid cooling
- Employs an advanced engineering polymers or materials for maximum fluid compatibility and long service life
- Made in USA

Thermal Mapping

In addition to its portfolio of Dynamic Cold Plates, Motivair also offers in-house thermal design to help leverage liquid-cooled cold plates for high-powered CPUs, GPUs, and FPGAs. Using advanced CFD software, Motivair can develop custom server-specific water loop designs based on your technology needs.

- Providing thermal solutions to enable the highest-powered processors in the IT industry
- Integrating into the most densely packed server designs on the market
- Facilitating the highest performance efficiencies and densities for HPC, AI and enterprise



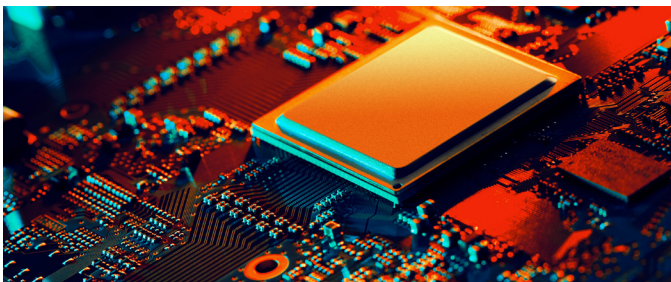
We cool the most advanced technology on the planet

We discover, design, and develop resilient thermal technologies and strategies, and convert that into actionable insights and unparalleled value for our clients.

From climate research to finance, cloud to artificial intelligence, customers trust Motivair's cooling technologies so they can break new boundaries and help deliver tomorrow's innovations faster.

We're helping our clients discover cures for diseases, combat climate change, and make tomorrow's data-driven services more reliable and accessible.

We are touching millions of lives each day by providing the critical cooling technology to support productivity and innovation that is changing our world.



DIRECT-TO-CHIP COOLING

Supercomputing isn't just in the lab anymore. The power of high-performance computing is scaling out as more enterprises and corporations look to utilize artificial intelligence for advanced decision-making and accelerate digital transformation.



DATA CENTER & IT COOLING

Designed for and used by the enterprise data center and supercomputer owners and operators, our cooling technology is engineered to help you leap forward in scale, quality, and speed.



THERMAL MANAGEMENT

When it comes to cooling your critical infrastructure, we work to customize specialty chiller technology for you, rather than selecting from a catalog



CLIENT SERVICES GROUP

Manage every aspect of your cooling infrastructure, from planning and design to start up, commissioning and post-sale performance. Your business depends not only on our products but also our ability to respond when you need us.